

WHAT IS CLAIMED IS:

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AI*
1. A solid-state image pickup device comprising:
a solid-state image pickup element chip on which a plurality of solid-state image pickup elements are mounted; and
a protection cap provided on a light incident side of said solid-state image pickup element chip and adapted to protect said solid-state image pickup element chip, characterized in that
 - 10 said solid-state image pickup element chip is formed on a substrate with a thermal expansion coefficient equal to that of said protection cap, and the substrate and said protection cap are sealed with a sealing resin.
 - 15 2. The device according to claim 1, characterized in that said solid-state image pickup element chip is adhered onto the substrate with a flexible adhesive.
 - 20 3. The device according to claim 1, characterized in that a contact preventive member is provided between each one of the plurality of solid-state image pickup elements and the sealing resin so the sealing resin will not come into contact with each one of the plurality of solid-state image pickup elements.
 - 25 4. The device according to claim 1, characterized

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In that the substrate is one of a glass substrate,
ceramic substrate, metal substrate, and resin
substrate, or a substrate formed by stacking some of
the glass substrate, ceramic substrate, metal
substrate, and resin substrate.

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5. The device according to claim 1, characterized
in that the sealing resin is a resin selected from the
group consisting of epoxy-, acrylic, and phenol-based
10 resins.

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6. The device according to claim 1, characterized
in that said solid-state image pickup element chip is
formed on the substrate through a light-shielding layer
15 that shields light.

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7. A solid-state image pickup device comprising:
a solid-state image pickup element chip on which a
plurality of solid-state image pickup elements are
20 mounted; and

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a protection cap provided on a light incident side
of said solid-state image pickup element chip and
adapted to protect said solid-state image pickup
element chip, characterized in that

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said solid-state image pickup element chip is
formed on a substrate made of the same material as that
of said protection cap, and

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the substrate and said protection cap are sealed
with a sealing resin.

8. The device according to claim 7, characterized
5 in that said solid-state image pickup element chip is
adhered onto the substrate with a flexible adhesive.

9. The device according to claim 7, characterized
in that a contact preventive member is provided between
10 each one of the plurality of solid-state image pickup
elements and the sealing resin so the sealing resin
will not come into contact with each one of the
plurality of solid-state image pickup elements.

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10. The device according to claim 7,
characterized in that the substrate is one of a glass
substrate, ceramic substrate, metal substrate, and
resin substrate, or a substrate formed by stacking some
of the glass substrate, ceramic substrate, metal
substrate, and resin substrate.
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11. The device according to claim 7,
characterized in that the sealing resin is a resin
selected from the group consisting of epoxy-, acrylic,
25 and phenol-based resins.

12. The device according to claim 7,

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characterized in that said solid-state image pickup
element chip is
formed on the substrate through a light-shielding layer
that shields light.

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